

2SK3335-VB Datasheet N-Channel 60 V (D-S) MOSFET

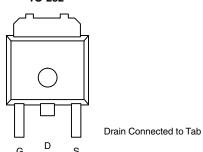
| PRODUCT SUMMARY | | | | | |
|---------------------|----------------------------------|--------------------|-----------------------|--|--|
| V _{DS} (V) | $R_{DS(on)}(\Omega)$ Max. | I _D (A) | Q _g (Typ.) | | |
| 60 | 0.073 at V _{GS} = 10 V | 18 | 19.8 | | |
| 00 | 0.085 at V _{GS} = 4.5 V | 15 | 19.0 | | |

FEATURES

- TrenchFET® Power MOSFET
- 100 % R_g and UIS Tested
- Material categorization: For definitions of compliance please see

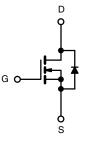






APPLICATIONS

- DC/DC Converters
- DC/AC Inverters
- **Motor Drives**



N-Channel MOSFET

| ABSOLUTE MAXIMUM RA | TINGS ($T_C = 25 ^{\circ}C$, unless of | otherwise noted) | | • | |
|--|--|-----------------------------------|-------------------|------|--|
| Parameter | | Symbol | Limit | Unit | |
| Drain-Source Voltage | V _{DS} | 60 | V | | |
| Gate-Source Voltage | | V _{GS} | ± 20 | _ V | |
| Continuous Drain Current | T _C = 25 °C | | 18 | | |
| Continuous Drain Current | T _C = 70 °C | I _D | 14 | A | |
| Pulsed Drain Current (t = 300 μs) | I _{DM} | 25 | A | | |
| Avalanche Current | | I _{AS} | 15 | | |
| Single Avalanche Energy ^a | L = 0.1 mH | E _{AS} | 11.25 | mJ | |
| Maximum Power Dissipation ^a | T _C = 25 °C | В | 41.7 ^b | w | |
| iviaximum Fower Dissipation | T _A = 25 °C ^c | P _D | 2.1 | VV | |
| Operating Junction and Storage Temperature | rature Range | T _J , T _{stg} | - 55 to 150 | °C | |

| THERMAL RESISTANCE RATINGS | | | | | |
|--|-------------------|-------|------|--|--|
| Parameter | Symbol | Limit | Unit | | |
| Junction-to-Ambient (PCB Mount) ^c | R _{thJA} | 60 | °C/W | | |
| Junction-to-Case (Drain) | R _{thJC} | 3 | C/VV | | |

Notes:

- a. Duty cycle \leq 1 %.
- b. See SOA curve for voltage derating.
- c. When mounted on 1" square PCB (FR-4 material).
- d. Base on T_C = 25 °C.

服务热线:400-655-8788

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| SPECIFICATIONS $(T_J = 25)$ | Symbol | Test Conditions | Min. | Typ. | Max. | Unit |
|---|----------------------|--|------|----------|-------|------|
| Static | 7, | | | | | |
| Drain-Source Breakdown Voltage | V _{DS} | V _{GS} = 0 V, I _D = 250 μA | 60 | | | |
| Gate Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$ | 1.0 | | 3.0 | V |
| Gate-Body Leakage | I _{GSS} | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$ | | | ± 250 | nA |
| | | V _{DS} = 60 V, V _{GS} = 0 V | | | 1 | |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} = 60 V, V _{GS} = 0 V, T _J = 125 °C | | | 50 | μΑ |
| | | V _{DS} = 60 V, V _{GS} = 0 V, T _J = 150 °C | | | 250 | - |
| On-State Drain Current ^a | I _{D(on)} | V _{DS} ≥ 10 V, V _{GS} = 10 V | 20 | | | Α |
| | _ ` ′ | V _{GS} = 10 V, I _D = 6.6 A | | 0.073 | | Ω |
| Drain-Source On-State Resistance ^a | R _{DS(on)} | V _{GS} = 4.5 V, I _D = 6 A | | 0.085 | | |
| Forward Transconductance ^a | 9 _{fs} | V _{DS} = 15 V, I _D = 6.6 A | | 25 | | S |
| Dynamic ^b | | | | <u> </u> | | |
| Input Capacitance | C _{iss} | | | 660 | | pF |
| Output Capacitance | C _{oss} | $V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$ | | 85 | | |
| Reverse Transfer Capacitance | C _{rss} | | | 40 | | |
| Total Gate Charge ^c | Qg | | | 19.8 | 30 | nC |
| Gate-Source Charge ^c | Q _{gs} | $V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 6.6 \text{ A}$ | | 3.6 | | |
| Gate-Drain Charge ^c | Q_{gd} | | | 4.1 | | |
| Gate Resistance | R _g | f = 1 MHz | 0.4 | 2 | 4 | Ω |
| Turn-On Delay Time ^c | t _{d(on)} | | | 8 | 16 | |
| Rise Time ^c | t _r | $V_{DD} = 30 \text{ V}, R_{L} = 9.6 \Omega$ | | 11 | 20 | |
| Turn-Off Delay Time ^c | t _{d(off)} | $I_D \cong 5.2 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$ | | 18 | 27 | |
| Fall Time ^c | t _f | | | 5 | 10 | |
| Turn-On Delay Time ^c | t _{d(on)} | | | 38 | 57 | ns |
| Rise Time ^c | t _r | $V_{DD} = 30 \text{ V}, R_{L} = 9.6 \Omega$ | | 58 | 87 | 1 |
| Turn-Off Delay Time ^c | t _{d(off)} | $I_D \cong 5.2 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$ | | 18 | 27 | |
| Fall Time ^c | t _f | | | 8 | 16 | |
| Drain-Source Body Diode Ratings a | nd Characteri | stics ^b T _C = 25 °C | | | | |
| Continuous Current | I _S | | | | 18 | Α |
| Pulsed Current | I _{SM} | | | | 25 | |
| Forward Voltage ^a | V _{SD} | I _F = 5.2 A, V _{GS} = 0 V | | 0.8 | 1.5 | V |
| Reverse Recovery Time | t _{rr} | | | 34 | 51 | ns |
| Peak Reverse Recovery Current | I _{RM(REC)} | I _F = 5.2 A, dI/dt = 100 A/μs | | 3 | 5 | Α |
| Reverse Recovery Charge | Q _{rr} | | | 50 | 75 | nC |

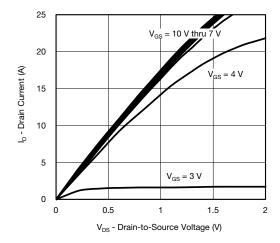
Notes:

- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

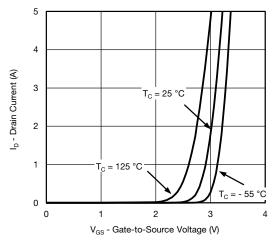
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



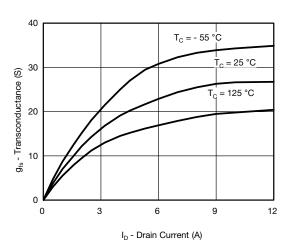
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



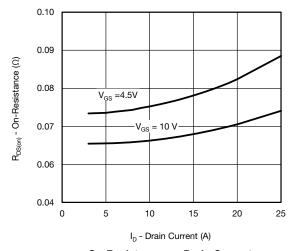
Output Characteristics



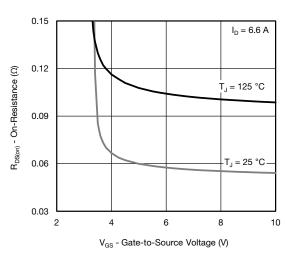
Transfer Characteristics



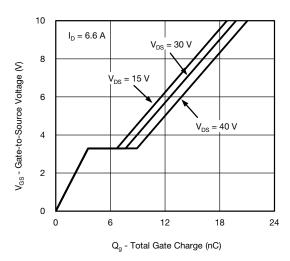
Transconductance



On-Resistance vs. Drain Current



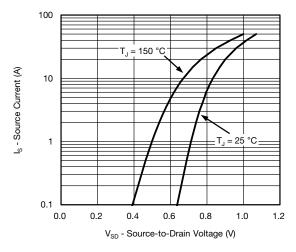
On-Resistance vs. Gate-to-Source Voltage



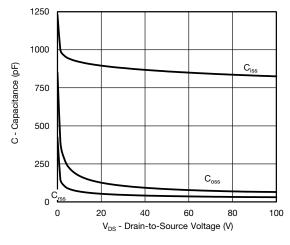
Gate Charge



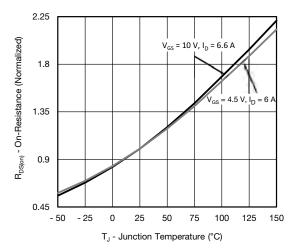
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



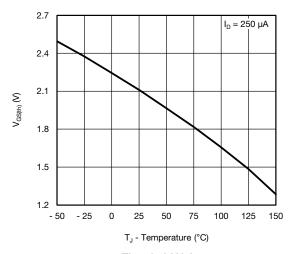
Source-Drain Diode Forward Voltage



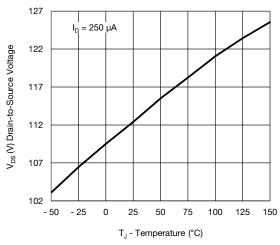
Capacitance



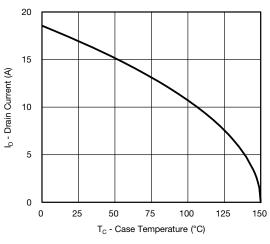
On-Resistance vs. Junction Temperature



Threshold Voltage



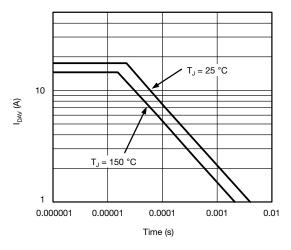
Drain Source Breakdown vs. Junction Temperature

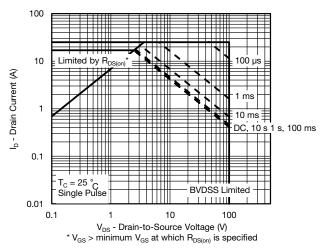


Current Derating



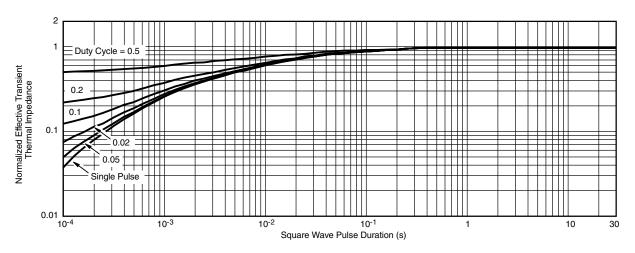
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





Single Pulse Avalanche Current Capability vs. Time

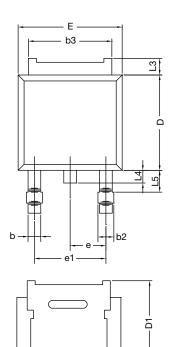
Safe Operating Area

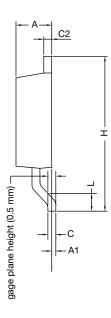


Normalized Thermal Transient Impedance, Junction-to-Case



TO-252AA Case Outline





| | MILLIN | METERS | INCHES | | |
|-----------|--------------|-----------|-----------|-------|--|
| DIM. | MIN. | MAX. | MIN. | MAX. | |
| А | 2.18 | 2.38 | 0.086 | 0.094 | |
| A1 | - | 0.127 | - | 0.005 | |
| b | 0.64 | 0.88 | 0.025 | 0.035 | |
| b2 | 0.76 | 1.14 | 0.030 | 0.045 | |
| b3 | 4.95 | 5.46 | 0.195 | 0.215 | |
| С | 0.46 | 0.61 | 0.018 | 0.024 | |
| C2 | 0.46 | 0.89 | 0.018 | 0.035 | |
| D | 5.97 | 6.22 | 0.235 | 0.245 | |
| D1 | 4.10 | - | 0.161 | - | |
| Е | 6.35 | 6.73 | 0.250 | 0.265 | |
| E1 | 4.32 | - | 0.170 | - | |
| Н | 9.40 | 10.41 | 0.370 | 0.410 | |
| е | 2.28 BSC | | 0.090 BSC | | |
| e1 | 4.56 BSC | | 0.180 BSC | | |
| L | 1.40 | 1.78 | 0.055 | 0.070 | |
| L3 | 0.89 | 1.27 | 0.035 | 0.050 | |
| L4 | - | 1.02 | - | 0.040 | |
| L5 | 1.01 | 1.52 | 0.040 | 0.060 | |
| ECN: T16- | 0236-Rev. P, | 16-May-16 | | | |

DWG: 5347

Notes

• Dimension L3 is for reference only.



RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)



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